

Ultra High Precision Z1 Foil Technology Flip Chip Resistor with standoff for Load Life Stability of 0.01% (100 ppm)

with TCR of ±2.5 ppm/°C,

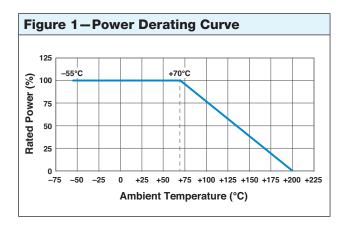
40% Space Saving vs. Wraparound Design, Power to 0.1W

FEATURES

- Temperature coefficient of resistance (TCR): ±2.5 ppm/°C Max (-55 °C to +125 °C, +25 °C ref.)
- Resistance range: 75 Ω up to 1 k Ω
- Tolerance: to ±0.05 % (500 ppm)
- Power rating: 0.1 W at +70 °C
- Load life stability: ±0.06% typical at +70 °C, 2000 h (rated power)
- · Non-inductive, non-capacitive design
- Short Time Overload ≤ 0.01 % (100 ppm)
- · Non hot spot design
- Gold finished solderable terminals, for high temperature applications
- Prototype quantities are available, please contact foil@vpgsensors.com

APPLICATIONS

- Medical
- Automatic Test Equipment (ATE)
- Measurement systems
- Telecommunications
- · Weighing systems
- Laboratory
- Industrial
- High Temperature Applications







INTRODUCTION

The FRFS is based on the new generation Z1 Foil Technology of the Bulk Metal® Precision Foil resistor elements by Vishay Precision Group (VPG),

The flip chip configuration provides a substantial PCB space saving 40 % vs. a surface mount chip with wraparound terminations.

The standoff construction allows visual inspection (VI) of the solder connection after mounting (this VI is impossible in standard flip chip construction due to close attachment to the PCB). Furthermore, this construction increases the rated power, due to enlarged heat dissipation through the thick terminals.

The FRFS is available in any value within the specified resistance range.

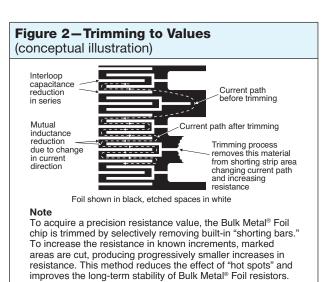




Table 1—Specifications							
Rated Power at +70°C (W)	Max. Working Voltage (≤√P × R, V)	Resistance Range (Ω)	Tolerance ⁽¹⁾ %	TCR max., (-55°C to +125°C, +25°C Ref.) (ppm/°C)	Max. Weight (mg)		
0.1	10	75 to 1k	to ±0.05	±2.5	1.3		
0.1	10	75 to 1K	10 ±0.03	±2.5	1.5		

Note

⁽¹⁾ For non-standard values and tighter Tolerance, please contact application engineering at foil@vpgsensors.com

Table 2—Performances (Based on MIL-PRF-55342 & MIL-PRF-32663) ⁽¹⁾						
Test	Conditions	Typical Limit % (ppm)	Max Limit % (ppm)			
Short Time Overload	6.25 x P _{nom}	±0.010 (100)	±0.020 (200)			
High Temperature Exposure	+150°C, 100 h	±0.003 (30)	±0.005 (50)			
Low Temperature Operation	-65°C, 45 min @ rated power (see table 1)	±0.001 (10)	±0.002 (20)			
Resistance to Soldering Heat	Per MIL-PRF-55342 (p.4.8.8.1)	±0.010 (100)	±0.015 (150)			
Moisture Resistance	Per MIL-PRF-55342 (p. 4.8.9)	±0.010 (100)	±0.015 (150)			
Load-Life Test, 70°C, 2,000 h	@ rated power (see Table 1)	±0.006 (60)	±0.010 (100)			
Thermal Shock	5 x (-65°C to +150°C)	±0.005 (50)	±0.010 (100)			
Thermal Shock	100 x (-65°C to +150°C)	±0.005 (50)	±0.010 (100)			

Note

⁽¹⁾ As shown +0.01 Ω to allow for measurement errors at low values.

